



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TESSERA 3.3-018

In 1996 patent application of  
Khandros et al.

Serial No.: 08/030,194

Filed: April 28, 1993

For: SEMICONDUCTOR CHIP ASSEMBLIES,  
METHODS OF MAKING SAME AND  
COMPONENTS FOR SAME

Assistant Commissioner For Patents  
Washington, D.C. 20231

: Group Art Unit: 2503

: Examiner: S. Clark

: Date: April 18, 1996

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RESPONSE

Sir:

In response to the Official Action mailed October 27, 1995,  
please amend the above-identified application as follows:

In the Claims:

In claim 1, line 1 change "chip comprising" to read --  
chip assembly comprising --.

Amend claim 63 as follows:

10 63. (Twice Amended) A module as claimed in claim  
62 wherein each said sheetlike element includes a thin, flexible,  
top layer and wherein said [complaint] compliant layer of each  
said sheetlike element is disposed between said top layer and  
said front surface of each said chip.

In claim 67, line 8 change "compressible" to read --  
compliant --.

In claim 68, line 10 change "compressible" to read --  
compliant --.

In claim 69, line 6 change "compressible" to read --  
compliant --.

I hereby certify that this correspondence is being deposited with the  
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